

PolySwitch Surface-mount

Resettable Devices

More than ten years ago, Raychem Circuit Protection introduced the SMD product family, and polymeric PTC devices quickly became the computer industry standard for keyboard, mouse, and disk drive protection. In 1995, Raychem Circuit Protection advanced the technology, reducing the size and cost of surface-mount resettable devices with the introduction of its miniSMD product series. The recent additions to the surface-mount family include the nanoSMD series, which reduces the size to a 3216mm (1206mils) foot print, one-third the size of the popular miniSMD series.



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Benefits:

- Smaller size saves board space and cost
- Many product choices give engineers more design flexibility
- Compatible with high-volume electronics assembly
- Assists in meeting regulatory requirements
- Higher voltage ratings allow use in new applications

Features:

- Broadest range of resettable devices available in the industry
- Current ratings from 0.05 to 3A
- Voltage ratings from 6V computer and electronic applications to 60V (600V Telecom)
- Agency recognition: UL, CSA, TÜV
- Small footprint
- Fast time-to-trip
- Low resistance

Applications:

- Computer motherboards
- Modems
- USB hub, ports and peripherals
- IEEE1394 ports
- Digital cameras
- Disk drives
- CD-ROMs
- Game machines
- Battery packs
- Phones
- Fax machines
- Analog and digital line cards
- Printers
- PDAs
- Chargers

Products in this section are grouped by:

Product Dimensions, Product Series, Hold Current

Step 1. Determine the circuit's operating parameters.

Fill in the following information about the circuit:

Maximum ambient operating temperature _____

Normal operating current _____

Maximum operating voltage
(i.e. miniSMDC014 is 60V_{DC} max.) _____

Maximum interrupt current _____

Step 2. Select the PolySwitch device that will accommodate the circuit's maximum ambient temperature and normal operating current.

Look across the top of Table S2 to find the temperature that most closely matches the circuit's maximum operating temperature. Look down that column to find the value equal to or greater than the circuit's normal operating current. Now look to the far left of that row to find the part number for the PolySwitch surface-mount device that will best accommodate the circuit. Devices in this section are grouped by device dimensions, so your operating-current requirement may be found in more than one grouping.

The thermal derating curves located in Figure S1 are the normalized representations of the data in Table S2.

Step 3. Compare the selected device's maximum electrical ratings with the circuit's maximum operating voltage and interrupt current.

Look down the first column of Table S3 to find the part number you selected in Step 2. Look to the right in that row to find the device's maximum operating voltage (V_{MAX}) and maximum interrupt current (I_{MAX}). Ensure that V_{MAX} and I_{MAX} are greater than or equal to the circuit's maximum operating voltage and maximum interrupt current.

Step 4. Determine time-to-trip.

Time-to-trip is the amount of time it takes for a device to switch to a high-resistance state once a fault current has been applied across the device. Identifying the PolySwitch device's time-to-trip is important in order to provide the desired protection capabilities. If the device you choose trips too fast, undesired or nuisance tripping will occur. If the device trips too slowly, the components being protected may be damaged before the device switches to a high-resistance state.

Figures S11-S19 show the typical time-to-trip at 20°C for each of the PolySwitch devices.

If the PolySwitch device's time-to-trip is too fast or too slow for the circuit, go back to Step 2 and choose an alternate device.

Step 5. Verify ambient operating conditions.

Ensure that your application's minimum and maximum ambient temperatures are within the operating temperature of -40°C to 85°C (-40°C to 125°C for SMDH160).

Step 6. Verify the PolySwitch device dimensions.

Using dimensions in Table S4, compare the dimensions of the PolySwitch device you selected with the application's space considerations.

Protection Application Selection Table for Surface-mount Devices

The table below lists Polyswitch devices typically used in these applications.

Specifications for the suggested device part numbers can be found in this section.

Once a part has been selected, the user should evaluate and test each product for the intended application.

PolySwitch Resettable Devices—Key Selection Criteria					
Protection Application	Additional Comments	Overcurrent Overvoltage	Small Size	Low Resistance	Fast Time-to-trip (Temperature Protection)
AC adapter input power	use w/ Zener & triac		SMD250	SMD250	SMD200
Battery pack protection			nanoSMDC150	miniSMDC260	miniSMDE190
Charger protection			nanoSMDM050	miniSMDM110/16	nanoSMDM075
CPU/IC protection			nanoSMDM100	nanoSMDC150	nanoSMDM075
Data acquisition/sensor			microSMD005	—	microSMD005
DC input/output power	≤6V		nanoSMDM075	nanoSMDC150	nanoSMDM050
	≤12V		miniSMDC075	miniSMDM110/16	miniSMDC075
DDC			nanoSMDM075	nanoSMDM100	nanoSMDM050
Device Bay system	DB12, DB20		miniSMDC200	miniSMDC260	miniSMDC200
	DB32		miniSMDC260	SMD300	miniSMDM200
Ethernet/Lan			nanoSMDM050	miniSMDM110/16	nanoSMDM075
Fan			microSMD035	microSMDC050	microSMD035
IEEE 802.3af	VOIP		SMD050-2018	SMD050-2018	SMD050-2018
IEEE-1394	power provider		SMD100/33	SMD185	SMD100/33
	alt. power provider		SMD185	SMD185	SMD150/33
	self-powered		SMD185	SMD185	SMD150/33
LCD inverter			nanoSMDM050	miniSMDM110/16	nanoSMDM075
LCD screen power			nanoSMDM050	nanoSMDM050	microSMD035
LNB (Low Noise Block)			SMD075	SMD075	SMD050
Motor	≤6V		nanoSMDM100	nanoSMDC150	microSMDM075
	≤13.2V		miniSMDC075	miniSMDM110/16	miniSMDC075
PS/2 mouse/keyboard			nanoSMDM075	nanoSMDM100	nanoSMDM050
Signal - data communication	≤6V		nanoSMDM075	nanoSMDM075	nanoSMDM075
	≤13.2V		miniSMDC050	miniSMDM075	miniSMDC020
	≤30V		SMD030-2018	SMD075	SMD050
SCSI			nanoSMDM100	nanoSMDC150	nanoSMDM075
Smart card reader			microSMD010	microSMDC035	microSMD005
Telecom - modem	UL1950	OC OV	TS600-170 TVB270SA or SC*	TS250-130 TVB270SA or SC*	TS600-170 TVB270SA or SC*
	ITU-T K.21	OC OV	TS250, TSV250 TVB270SA*	TS250, TSV250-130 TVB270SA*	TS250-130-RB TVB270SA*
	Digital line	OC OV	miniSMDC014 TVB270SC*	miniSMDC014 TVB270SC*	miniSMDC014 TVB270SC*
Telecom - PBX	UL1950	OC OV	TS600-170 TVB270SA or SC*	TS600-200-RA TVB270SA or SC*	TS600-170 TVB270SA or SC*
	ITU-T K.21	OC OV	TS250, TSV250 TVB270SA*	TS250-130 TVB270SA*	TS250-130-RB TVB270SA*
	Subscriber	OC	miniSMDC014	miniSMDC014	miniSMDC014
Telecom - line card	Telcordia	OC	TS600-200-RA-B-0.5	TS600-200-RA-B-0.5	TS600-200-RA-B-0.5
	GR-1089	OV	TVB270SC*	TVB270SC*	TVB270SC*
	ITU-T K.20	OC OV	TS250, TSV250 TVB270SA*	TS250-130-RA TVB270SA*	TS250 TVB270SA*
Intrabuilding protection	Telcordia GR1089		TSL250-080	SMD030-2018	TSL250-080
Temperature sensor	CPU		nanoSMDM050	nanoSMDM075	nanoSMDM050
USB	Individual Port		nanoSMDM075	nanoSMDM100	nanoSMDM050
	2 port ganged		nanoSMDC150	miniSMDC150	miniSMDC125
	3 port ganged		miniSMDC200	miniSMDM200	miniSMDM200

*Refer to the SiBar thyristor product section for more information.

This list is not exhaustive. Raychem Circuit Protection welcomes our customers' input for additional application ideas for Polyswitch Resettable devices.

Table S1. Product Series: Size, Current Rating, Voltage Rating/Typical Resistance for Surface-mount Devices

	nanoSMDC nanoSMDM	microSMD	miniSMDC miniSMDM	midSMD	SMD	SMD2	miniSMDE	TS250 TSL250 TSV250	TS600
Size mm (mils)	3216 (1206)	3225 (1210)	4532 (1812)	5050 (2018)	7555 (2920)	8763 (3425)	11550 (4420)	*	*
Hold Current (A)	—	—	—	—	—	—	—	—	—
0.05	—	30V _{DC} /25Ω	—	—	—	—	—	—	—
0.08	—	—	—	—	—	—	—	80V/12.5Ω	—
0.100	30V _{DC} /12Ω	—	—	—	—	—	—	—	—
0.125	30V _{DC} /—	—	—	—	—	—	—	—	—
0.13	—	—	—	—	—	—	—	60V/6.0-8.0Ω	—
0.14	—	—	60V _{DC} /4.0Ω	—	—	—	—	—	—
0.160	30V _{DC} /—	—	—	—	—	—	—	—	—
0.17	—	—	—	—	—	—	—	—	60V/11.0Ω
0.18	—	—	—	—	—	—	—	—	—
0.20	24V _{DC} /—	—	30V _{DC} /1.4Ω	—	—	—	—	—	60V/8.5Ω
0.30	—	—	—	60V _{DC} /1.4Ω	60V _{DC} /3.0Ω	—	—	—	—
0.35	—	6V _{DC} /0.81Ω	—	—	—	—	—	—	—
0.50	6V _{DC} /0.40Ω	13.2V _{DC} /0.55Ω	24V _{DC} /0.60Ω	57V _{DC} /0.5Ω	60V _{DC} /0.87Ω	—	—	—	—
0.75	6V _{DC} /0.20Ω	6V _{DC} /0.29Ω	13.2V _{DC} /0.23Ω	—	30V _{DC} /0.67Ω	—	—	—	—
24V _{DC} /0.20Ω	—	—	24V _{DC} /0.20Ω	—	—	—	—	—	—
1.00	6V _{DC} /0.15Ω	—	—	15V _{DC} /0.25Ω	30V _{DC} /0.30Ω	—	—	—	—
33V _{DC} /0.27Ω	—	—	—	—	—	—	—	—	—
1.10	6V _{DC} /—	6V _{DC} /0.14Ω	6V _{DC} /0.12Ω	—	—	—	—	—	—
8V _{DC} /0.14Ω	—	—	8V _{DC} /0.12Ω	—	—	—	—	—	—
16V _{DC} /0.12Ω	—	—	16V _{DC} /0.12Ω	—	—	—	—	—	—
1.25	—	—	6V _{DC} /0.09Ω	—	15V _{DC} /0.16Ω	—	—	—	—
1.50	6V _{DC} /0.08Ω	6V _{DC} /0.07Ω	6V _{DC} /0.07Ω	15V _{DC} /0.13Ω	—	15V _{DC} /0.16Ω	—	—	—
33V _{DC} /0.15Ω	—	—	—	—	—	33V _{DC} /0.12Ω	—	—	—
1.60	—	—	8V _{DC} /0.066Ω	—	—	16V _{DC} /0.10Ω	—	—	—
1.85	—	—	—	—	—	33V _{DC} /0.12Ω	—	—	—
1.90	—	—	—	—	—	—	16V _{DC} /0.065Ω	—	—
2.00	—	—	6V _{DC} /0.050Ω	6V _{DC} /0.07Ω	—	15V _{DC} /0.09Ω	—	—	—
8V _{DC} /0.040Ω	—	—	8V _{DC} /0.040Ω	—	—	—	—	—	—
2.50	—	—	—	—	—	15V _{DC} /0.06Ω	—	—	—
2.60	—	—	6V _{DC} /0.035Ω	—	6V _{DC} /0.05Ω	—	—	—	—
6V _{DC} /0.030Ω	—	—	—	—	—	—	—	—	—
3.00	—	—	—	—	6V _{DC} /0.033Ω	—	—	—	—

*Refer to Telecommunications and Networking section for dimensions; voltage for these parts is RMS max.

**Table S2-A. Thermal Derating for Surface-mount Devices [Hold Current (A) at Ambient Temperature (°C)]
continued**

Part Number	Maximum Ambient Temperature											
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C	125°C
midSMD Size 5050 mm/2018 mils												
SMD030-2018	0.48	0.42	0.35	0.30	0.28	0.24	0.21	0.17	0.15	0.12	0.10	—
SMD050-2018	0.86	0.77	0.70	0.55	0.53	0.48	0.43	0.38	0.36	0.29	0.26	—
SMD100-2018	1.59	1.43	1.20	1.10	1.03	0.94	0.85	0.72	0.69	0.61	0.57	—
SMD150-2018	2.21	1.97	1.70	1.50	1.43	1.26	1.15	1.00	0.91	0.79	0.73	—
SMD200-2018	2.81	2.54	2.27	2.00	1.93	1.73	1.59	1.46	1.32	1.19	1.12	—
Lead-free devices are listed in Table S2-B												
SMD Size 7555 mm/2920 mils												
SMD030	0.44	0.39	0.32	0.30	0.28	0.26	0.23	0.19	0.18	0.17	0.15	—
SMD050	0.73	0.65	0.55	0.50	0.47	0.43	0.39	0.33	0.31	0.28	0.26	—
SMD075	1.11	0.99	0.84	0.75	0.71	0.63	0.57	0.49	0.45	0.39	0.36	—
SMD100	1.59	1.43	1.20	1.10	1.03	0.94	0.85	0.72	0.69	0.61	0.57	—
SMD100/33	1.48	1.35	1.20	1.10	1.06	0.98	0.91	0.83	0.79	0.73	0.69	—
SMD125	1.89	1.68	1.50	1.25	1.21	1.04	0.93	0.85	0.71	0.61	0.55	—
SMD260	3.82	3.41	2.90	2.60	2.45	2.19	1.99	1.70	1.58	1.38	1.28	—
SMD260-RB	3.82	3.41	2.90	2.60	2.45	2.19	1.99	1.70	1.58	1.38	1.28	—
SMD300	4.13	3.75	3.30	3.00	2.87	2.62	2.43	2.25	2.00	1.87	1.78	—
Lead-free devices are listed in Table S2-B												
SMD2 Size 8763 mm/3425 mils												
SMD150	2.30	2.04	1.80	1.50	1.45	1.23	1.10	0.99	0.83	0.70	0.63	—
SMD150/33	2.30	2.04	1.80	1.50	1.45	1.23	1.10	0.99	0.83	0.70	0.63	—
SMDH160	2.15	1.96	1.78	1.60	1.55	1.42	1.33	1.24	1.15	1.05	1.01	0.64
SMD185	2.54	2.29	2.20	1.85	1.80	1.55	1.43	1.31	1.19	1.06	1.00	—
SMD200	3.01	2.67	2.30	2.00	1.90	1.66	1.50	1.30	1.16	0.99	0.91	—
SMD250	3.72	3.31	2.80	2.50	2.35	2.09	1.89	1.60	1.48	1.28	1.18	—
Lead-free devices are listed in Table S2-B												
Telecom Surface-mount												
TSL250-080	0.124	0.110	0.095	0.080	0.077	0.066	0.059	0.051	0.044	0.037	0.033	—
TS250-130	0.208	0.182	0.156	0.130	0.124	0.104	0.091	0.078	0.065	0.052	0.045	—
TSV250-130	0.208	0.182	0.156	0.130	0.124	0.104	0.091	0.078	0.065	0.052	0.045	—
TS600-170	0.264	0.230	0.200	0.170	0.163	0.140	0.125	0.109	0.094	0.077	0.070	—
TS600-200-RA	0.310	0.275	0.238	0.200	0.193	0.165	0.147	0.128	0.110	0.091	0.083	—
TSM600-250	0.400	0.350	0.300	0.250	0.241	0.198	0.170	0.141	0.117	0.097	0.083	—

**Table S2-B. Thermal Derating for Lead-free Surface-mount Devices
[Hold Current (A) at Ambient Temperature (°C)]**

Part Number	Maximum Ambient Temperature											
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C	125°C
Lead-free nanoSMDC Series Size 3216 mm/1206 mils												
nanoSMDC020F	0.34	0.30	0.26	0.22	0.20	0.17	0.15	0.13	0.11	0.09	0.08	—
nanoSMDC035F	0.58	0.51	0.44	0.38	0.35	0.31	0.28	0.24	0.21	0.18	0.16	—
nanoSMDC050F/13.2	0.78	0.69	0.61	0.52	0.50	0.44	0.39	0.35	0.30	0.25	0.24	—
nanoSMDC075F	1.15	1.04	0.92	0.78	0.75	0.69	0.63	0.58	0.51	0.46	0.43	—

**Table S2-B. Thermal Derating for Lead-free Surface-mount Devices [Hold Current (A) at Ambient Temperature (°C)]
continued**

Part Number	Maximum Ambient Temperature											
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C	125°C
Lead-free SMD Series Size 5050 mm/2018 mils												
SMD030F-2018	0.48	0.42	0.35	0.30	0.28	0.24	0.21	0.17	0.15	0.12	0.10	—
SMD050F-2018	0.86	0.77	0.70	0.55	0.53	0.48	0.43	0.38	0.36	0.29	0.26	—
SMD100F-2018	1.59	1.43	1.20	1.10	1.03	0.94	0.85	0.72	0.69	0.61	0.57	—
SMD150F-2018	2.21	1.97	1.70	1.50	1.43	1.26	1.15	1.00	0.91	0.79	0.73	—
SMD200F-2018	2.81	2.54	2.27	2.00	1.93	1.73	1.59	1.46	1.32	1.19	1.12	—
Lead-free SMD Series Size 7555 mm/2920 mils												
SMD030F	0.44	0.39	0.32	0.30	0.28	0.26	0.23	0.19	0.18	0.17	0.15	—
SMD050F	0.73	0.65	0.55	0.50	0.47	0.43	0.39	0.33	0.31	0.28	0.26	—
SMD075F	1.11	0.99	0.84	0.75	0.71	0.63	0.57	0.49	0.45	0.39	0.36	—
SMD075F/60	1.11	0.99	0.84	0.75	0.71	0.63	0.57	0.49	0.45	0.39	0.36	—
SMD100F	1.59	1.43	1.20	1.10	1.03	0.94	0.85	0.72	0.69	0.61	0.57	—
SMD100F/33	1.48	1.35	1.20	1.10	1.06	0.98	0.91	0.83	0.79	0.73	0.69	—
SMD125F	1.89	1.68	1.50	1.25	1.21	1.04	0.93	0.85	0.71	0.61	0.55	—
SMD260F	3.82	3.41	2.90	2.60	2.45	2.19	1.99	1.70	1.58	1.38	1.28	—
SMD300F	4.13	3.75	3.30	3.00	2.87	2.62	2.43	2.25	2.00	1.87	1.78	—
Lead-free SMD2 Series Size 8763 mm/3425 mils												
SMD150F	2.30	2.04	1.80	1.50	1.45	1.23	1.10	0.99	0.83	0.70	0.63	—
SMD150F/33	2.30	2.04	1.80	1.50	1.45	1.23	1.10	0.99	0.83	0.70	0.63	—
SMD185F	2.54	2.29	2.20	1.85	1.80	1.55	1.43	1.31	1.19	1.06	1.00	—
SMD200F	3.01	2.67	2.30	2.00	1.90	1.66	1.50	1.30	1.16	0.99	0.91	—
SMD250F	3.72	3.31	2.80	2.50	2.35	2.09	1.89	1.60	1.48	1.28	1.18	—

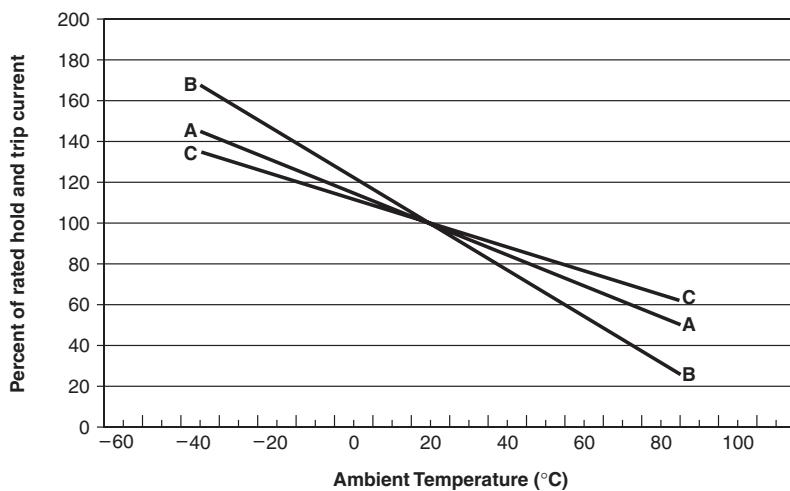
Thermal Derating Curves for Surface-mount Devices*

A = nanoSMD/microSMD/miniSMD & SMD

B = miniSMDE190

C = SMDH160

Figure S1. Thermal Derating Curve



*Refer to Telecom and Networking section for thermal derating of Telecom parts.

Table S3-A. Electrical Characteristics for Surface-mount Devices at 20°C continued

Part Number	I _H (A)	I _T (A)	V _{MAX} (V _{DC})	I _{MAX} (A)	P _{D TYP} (W)	Max. Time-to-Trip (A)	R _{MIN} Ω	R _{TYP} Ω	R _{1 MAX} Ω	Figure for Dimensions
midSMD										
Size 5050 mm/2018 mils										
SMD030-2018	0.30	0.80	60	20	0.7	1.5	1.5	0.500	1.40	2.300
SMD050-2018	0.55	1.20	57	10	1.0	2.5	5.0	0.200	—	1.000
SMD100-2018	1.10	2.20	15	40	1.2	8.0	0.5	0.100	0.25	0.400
SMD150-2018	1.50	3.00	15	40	1.4	8.0	1.0	0.070	0.13	0.180
SMD200-2018	2.00	4.20	6	40	1.4	8.0	3.0	0.048	0.07	0.100

SMD
Size 7555 mm/2920 mils

SMD030	0.30	0.60	60	10	1.5	1.5	3.0	1.200	3.00	4.800
SMD050	0.50	1.00	60	10	1.5	2.5	4.0	0.350	0.87	1.400
SMD075	0.75	1.50	30	40	1.5	8.0	0.3	0.350	0.67	1.000
SMD100	1.10	2.20	30	40	1.5	8.0	0.5	0.120	0.30	0.480
SMD100/33	1.10	2.20	33	40	1.5	8.0	0.5	0.120	0.27	0.410
SMD125	1.25	2.50	15	40	1.5	8.0	2.0	0.070	0.16	0.250
SMD260	2.60	5.20	6	40	1.5	8.0	20.0	0.025	0.05	0.075
SMD260-RB	2.60	5.00	6	40	1.5	5.0	60.0	0.030	0.055	0.075
SMD300	3.00	6.00	6	40	1.3	8.0	35.0	0.015	0.033	0.048

Lead-free devices are listed in Table S3-B

SMD2
Size 8763 mm/3425 mils

SMD150	1.50	3.00	15	40	1.7	8.0	5.0	0.060	0.16	0.250
SMD150/33	1.50	3.00	33	40	1.7	8.0	5.0	0.080	0.15	0.230
SMDH160	1.60	3.20	16	70	2.1	8.0	15.0	0.050	0.10	0.150
SMD185	1.80	3.60	33	40	1.2	8.0	5.0	0.065	0.12	0.165
SMD200	2.00	4.00	15	40	1.7	8.0	12.0	0.050	0.09	0.125
SMD250	2.50	5.00	15	40	1.7	8.0	25.0	0.035	0.06	0.085

Lead-free devices are listed in Table S3-B

Part Number	I _H (A)	I _T (A)	V _{MAX} (V _{RMS})	I _{MAX} (A)	P _{D TYP} (W)	Max. Time-to-Trip (A)	R _{MIN} Ω	R _{TYP} Ω	R _{1 MAX} Ω	Figure for Dimensions
Telecom Surface-mount										
TSL250-080										
TSL250-080	0.080	0.16	250	3.0	1.2	1.0	0.8	5.0	11.0	20.0
TSL250-080	0.130	0.26	250	3.0	1.1	1.0	0.9	6.5	12.0	20.0
TSL250-130	—	—	650	1.1	—	—	—	—	—	—
TSV250-130	0.130	0.26	250	3.0	1.5	1.0	2.0	4.0	7.0	12.0
TS600-170	0.170	0.40	600	3.0	2.5	1.0	10.0	4.0	9.0	18.0
TS600-200-RA	0.200	0.40	600	3.0	2.5	1.0	12.0	4.0	7.5	13.5
TSM600-250	0.250	0.86	600	3.0	2.0	3.0	8.0	1.0	3.5	7.0

Table S3-B. Electrical Characteristics for Lead-free Surface-mount Devices at 20°C

Part Number	I _H (A)	I _T (A)	V _{MAX} (V _{DC})	I _{MAX} (A)	P _{D TYP} (W)	Max. Time-to-Trip (A)	R _{MIN} Ω	R _{TYP} Ω	R _{1 MAX} Ω	Figure for Dimensions
Lead-free nanoSMDC Series Size 3216 mm/1206 mils										
nanoSMDC020F [†]	0.20	0.42	24	100	0.6	8.0	0.10	0.65	—	2.600
nanoSMDC035F [†]	0.35	0.75	16	20	0.6	3.5	0.10	0.45	—	1.400
nanoSMDC050F/13.2 [†]	0.50	1.10	13.2	40	0.6	8.0	0.10	0.20	—	0.800
nanoSMDC075F [†]	0.75	1.50	6	40	0.6	8.0	0.10	0.12	—	0.400
nanoSMDC110F	1.10	2.20	6	40	0.6	8.0	0.10	0.07	—	0.200
nanoSMDC150F [†]	1.50	3.00	6	40	0.6	8.0	0.30	0.04	0.080	0.110
Lead-free nanoSMDM Series Size 3216 mm/1206 mils										
nanoSMDM012F [†]	0.125	0.29	30	10	0.4	1.0	0.20	1.50	4.5	6.000
nanoSMDM020F [†]	0.20	0.46	24	10	0.4	1.0	0.60	0.65	—	2.600
nanoSMDM050F [†]	0.50	1.00	6	40	0.4	8.0	0.10	0.15	0.400	0.700
nanoSMDM050F/13.2 [†]	0.50	1.00	13.2	40	0.4	8.0	0.10	0.15	0.400	0.700
nanoSMDM075F [†]	0.75	1.50	6	40	0.4	8.0	0.20	0.10	0.200	0.290
nanoSMDM100F [†]	1.00	1.80	6	40	0.4	8.0	0.30	0.06	0.150	0.210
Lead-free microSMD Series Size 3225 mm/1210 mils										
microSMD005F	0.05	0.15	30	10	0.6	0.25	1.5	3.60	25.00	50.000
microSMD010F	0.10	0.25	30	10	0.6	0.5	1.0	2.10	9.00	15.000
microSMD035F	0.35	0.75	6	40	0.6	8.0	0.2	0.33	0.81	1.300
microSMD050F	0.50	1.00	13.2	40	0.6	5.0	0.1	0.25	0.55	0.900
microSMD075F	0.75	1.50	6	40	0.6	8.0	0.1	0.11	0.29	0.400
microSMD110F	1.10	2.20	6	40	0.6	5.0	1.0	0.07	0.14	0.210
microSMD150F	1.50	3.00	6	40	0.6	5.0	5.0	0.04	0.07	0.110
Lead-free miniSMDC Series Size 4532 mm/1812 mils										
miniSMDC014F	0.14	0.34	60	10	0.6	1.5	0.15	1.500	4.000	6.000
miniSMDC020F	0.20	0.40	30	10	0.6	8.0	0.02	0.600	2.900	3.300
miniSMDC050F	0.50	1.00	24	100	0.6	8.0	0.15	0.150	0.600	1.000
miniSMDC075F	0.75	1.50	13.2	100	0.6	8.0	0.20	0.110	0.260	0.450
miniSMDC110F	1.10	2.20	8	100	0.6	8.0	0.30	0.040	0.120	0.210
miniSMDC110F/16	1.10	2.20	16	100	0.3	8.0	0.30	0.060	—	0.180
miniSMDC125F	1.25	2.50	6	100	0.6	8.0	0.40	0.050	0.090	0.140
miniSMDC125F/16	1.25	2.50	16	100	0.6	8.0	0.40	0.050	0.090	0.140
miniSMDC150F	1.50	3.00	6	100	0.6	8.0	0.50	0.040	0.070	0.110
miniSMDC160F	1.60	3.20	6	100	0.6	8.0	1.00	0.030	0.078	0.100
miniSMDC200F	2.00	4.00	6	100	0.6	8.0	5.00	0.020	0.050	0.070
miniSMDC260F	2.60	5.00	6	100	0.6	8.0	7.00	0.015	0.035	0.047
miniSMDC260F/12	2.60	5.00	12	100	0.6	8.0	5.00	0.015	0.035	0.047
Lead-free miniSMDM Series Size 4532 mm/1812 mils										
miniSMDM075F/24 [†]	0.75	1.50	24	40	0.6	8.0	0.30	0.090	0.200	0.290
miniSMDM110F [†]	1.10	2.00	8	40	0.5	8.0	0.30	0.060	0.140	0.180
miniSMDM110F/16 [†]	1.10	1.95	16	40	0.6	8.0	0.50	0.060	0.120	0.180
miniSMDM200F [†]	2.00	3.50	8	40	0.6	8.0	3.00	0.020	0.040	0.060
miniSMDM260F [†]	2.60	4.55	6	40	0.6	8.0	6.00	0.010	0.030	0.043
Lead-free midSMD Series Size 5050 mm/2018 mils										
SMD030F-2018	0.30	0.80	60	20	0.9	1.5	1.50	0.500	1.400	2.300
SMD100F-2018	1.10	2.20	15	40	1.2	8.0	0.50	0.100	0.250	0.400

[†]Electrical characteristics determined at 25°C.

Table S3-B. Electrical Characteristics for Lead-free Surface-mount Devices at 20°C continued

Part Number	I _H (A)	I _T (A)	V _{MAX} (V _{DC})	I _{MAX} (A)	P _{D TYP} (W)	Max. Time-to-Trip (A)	R _{MIN} Ω	R _{TYP} Ω	R _{1 MAX} Ω	Figure for Dimensions
SMD150F-2018	1.50	3.00	15	40	1.4	8.0	1.00	0.070	0.130	0.180
SMD200F-2018	2.00	4.20	6	40	1.4	8.0	3.00	0.048	0.700	0.100
Lead-free SMD Series Size 7555 mm/2920 mils										
SMD030F	0.30	0.60	60	10	1.5	1.5	3.0	1.200	3.00	4.800
SMD050F	0.50	1.00	60	10	1.5	2.5	4.0	0.350	0.87	1.400
SMD075F	0.75	1.50	30	40	1.5	8.0	0.3	0.350	0.67	1.000
SMD075F/60	0.75	1.50	60	10	1.5	8.0	0.3	0.350	0.67	1.000
SMD100F	1.10	2.20	30	40	1.5	8.0	0.5	0.120	0.30	0.480
SMD100F/33	1.10	2.20	33	40	1.5	8.0	0.5	0.120	0.27	0.410
SMD125F	1.25	2.50	15	40	1.5	8.0	2.0	0.070	0.16	0.250
SMD260F	2.60	5.20	6	40	1.5	8.0	20.0	0.025	0.05	0.075
SMD300F	3.00	5.00	6	40	1.3	8.0	35.0	0.015	0.033	0.048
Lead-free SMD2 Devices Size 8763 mm/3425 mils										
SMD150F	1.50	3.00	15	40	1.7	8.0	5.0	0.060	0.16	0.250
SMD150F/33	1.50	3.00	33	40	1.7	8.0	5.0	0.080	0.15	0.230
SMD185F	1.80	3.60	33	40	1.2	8.0	5.0	0.065	0.12	0.165
SMD200F	2.00	4.00	15	40	1.7	8.0	12.0	0.050	0.09	0.125
SMD250F	2.50	5.00	15	40	1.7	8.0	25.0	0.035	0.06	0.085

Figures S2–S10. Physical Description for Dimensions for Surface-mount Devices

Figure S2

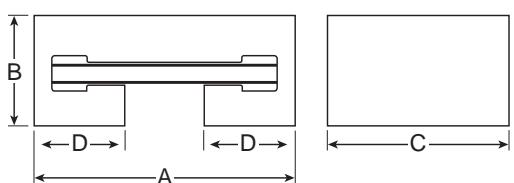


Figure S3

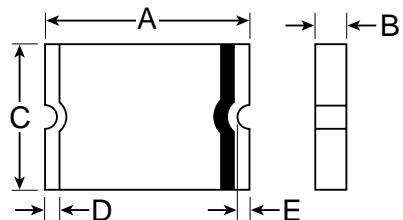


Figure S4

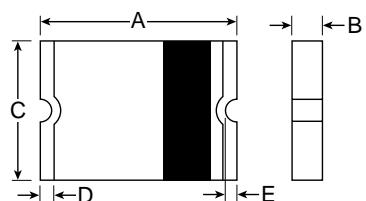


Figure S5

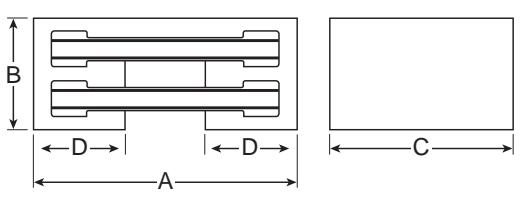


Figure S6

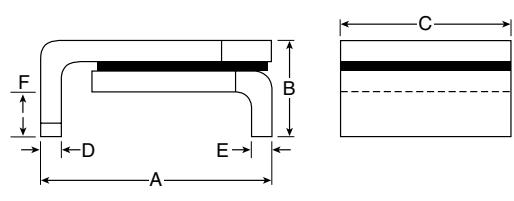


Figure S7

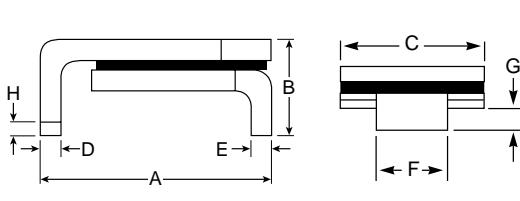


Figure S8

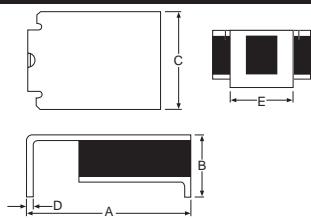


Figure S9

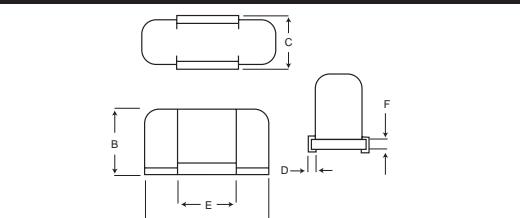
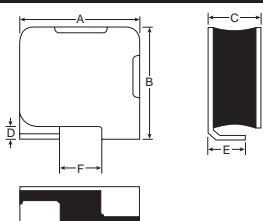


Figure S10



Figures S11–S19. Typical Time-to-trip Curves at 20°C for Surface-mount Devices

Telecom and Networking Devices

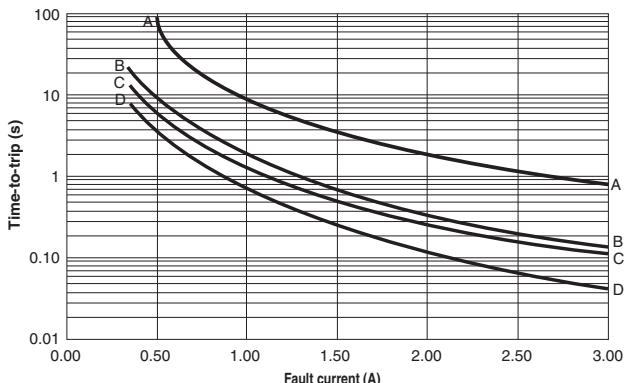
A = TS600-170/TS600-200

B = TS250-130

C = TSV250-130

D = TSL250-080

Figure S11



nanoSMDC and nanoSMDCxxxF

A = nanoSMDC020F

B = nanoSMDC035F

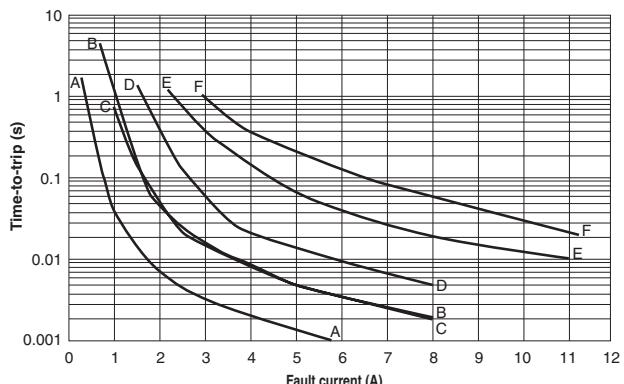
C = nanoSMDC050F/13.2

D = nanoSMDC075F

E = nanoSMDC110F

F = nanoSMDC150,
nanoSMDC150F

Figure S12



nanoSMDM and nanoSMDMxxxF

A = nanoSMDM012,
nanoSMDM012F

B = nanoSMDM016

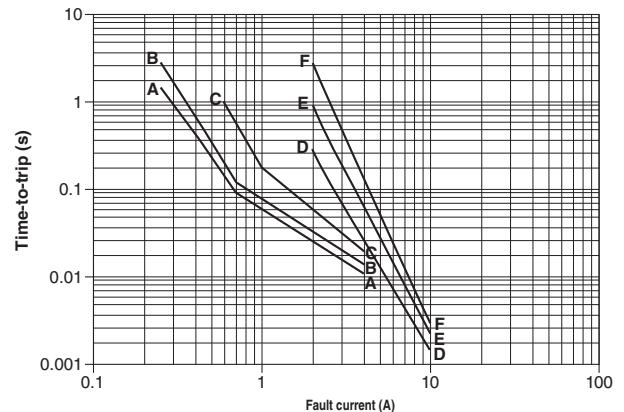
C = nanoSMDM020F

D = nanoSMDM050,
nanoSMDM050F,
nanoSMDM050F/13.2

E = nanoSMDM075,
nanoSMDM075F

F = nanoSMDM100,
nanoSMDM100F

Figure S13



Figures S11–S19. Typical Time-to-trip Curves at 20°C for Surface-mount Devices *continued*microSMD and microSMDF

A = microSMD005,
microSMD005F

B = microSMD010,
microSMD010F

C = microSMD035,
microSMD035F

D = microSMD050,
microSMD050F

E = microSMD075,
microSMD075F

F = microSMD110,
microSMD110F

G = microSMD150,
microSMD150F

miniSMDM and miniSMDMxxxF
(data at 25°C)

A = miniSMDM075,
miniSMDM075/24,
miniSMDM075F/24

B = miniSMDM110,
miniSMDM110F,
miniSMDM110/16,
miniSMDM110F/116

C = miniSMDM150/24

D = miniSMDM160

E = miniSMDM200,
miniSMDM200F

F = miniSMDM260,
miniSMDM260F

miniSMDC, miniSMDCxxxF and
miniSMDE

A = miniSMDC014, miniSMDC014F

B = miniSMDC020, miniSMDC020F

C = miniSMDC050, miniSMDC050F

D = miniSMDC075, miniSMDC075F

E = miniSMDC110, miniSMDC110F,
miniSMDC110F/16

F = miniSMDC125, miniSMDC125F,
miniSMDC125F/16

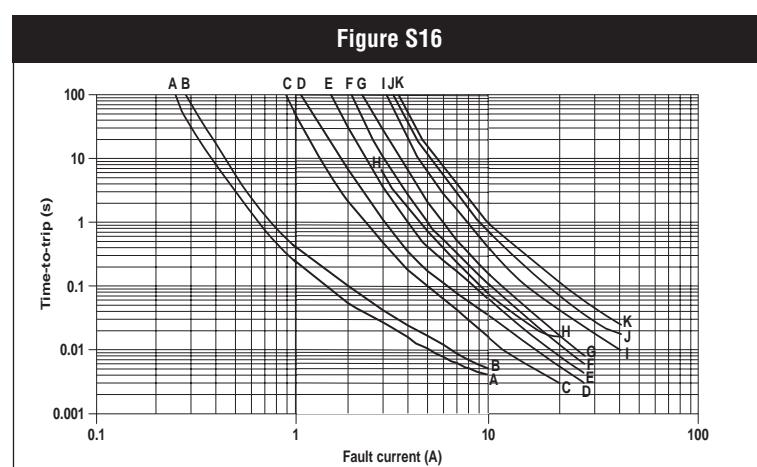
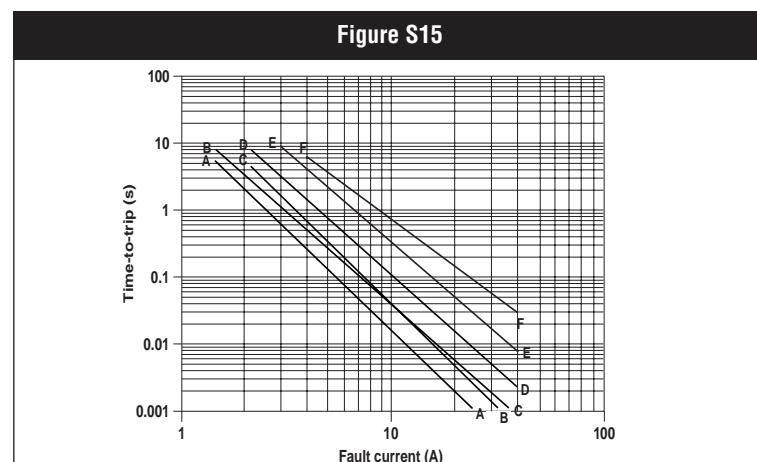
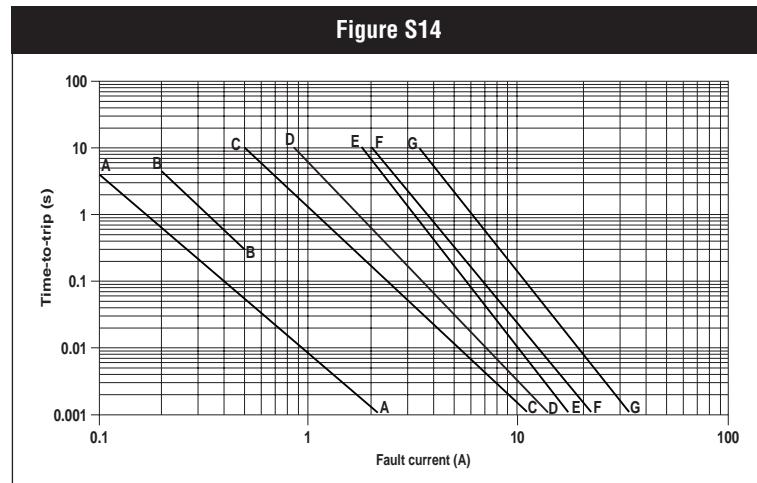
G = miniSMDC150, miniSMDC150F

H = miniSMDC160F

I = miniSMDC200, miniSMDC200F

J = miniSMDE190

K = miniSMDC260, miniSMDC260F,
miniSMDC260F/12



Figures S11–S19. Typical Time-to-Trip Curves at 20°C for Surface-mount Devices

midSMD

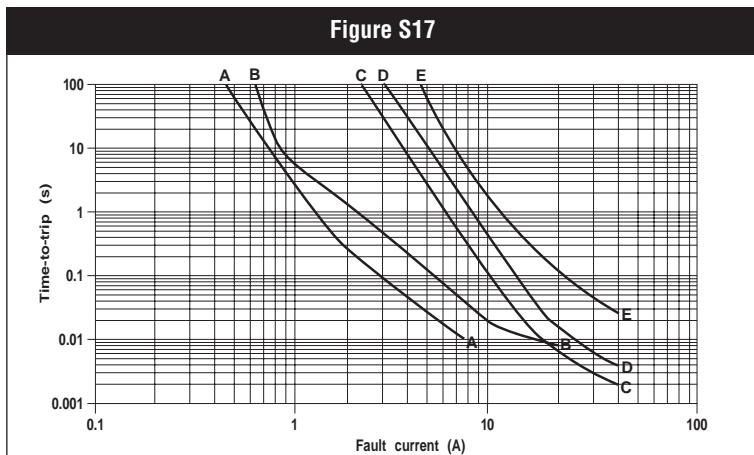
A = SMD030-2018,
SMD030F-2018

B = SMD050-2018

C = SMD100-2018,
SMD100F-2018

D = SMD150-2018,
SMD150F-2018

E = SMD200-2018,
SMD200F-2018



SMD and SMDxxxF

A = SMD030, SMD030F

B = SMD050, SMD050F

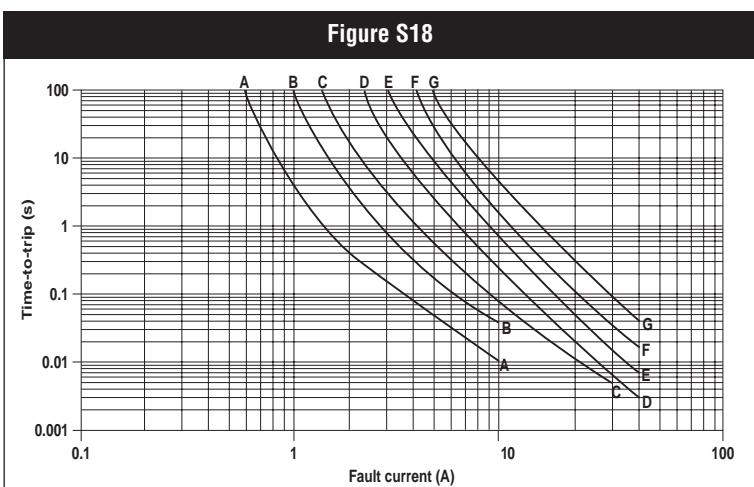
C = SMD075, SMD075F,
SMD075F/60

D = SMD100, SMD100F,
SMD100/33, SMD100F/33

E = SMD125, SMD125F

F = SMD260, SMD260RB,
SMD260F

G = SMD300, SMD300F



SMD2 and SMDxxxF

A = SMD150, SMD150F,
SMD150/33, SMD150F/33

B = SMDH160

C = SMD185, SMD185F

D = SMD200, SMD200F

E = SMD250, SMD250F

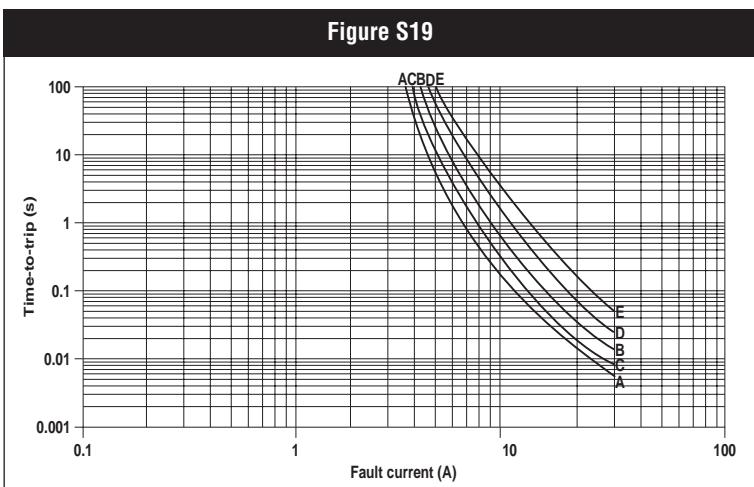


Table S5. Physical Characteristics and Environmental Specifications for Surface-mount Devices
Operating temperature range -40°C to 85°C, -40°C to 125°C for SMDH160

Physical Characteristics	
Terminal pad material	Solder-plated copper for nanoSMDC, microSMD, and miniSMDC series Gold plating for nanoSMDM, and miniSMDM series 100% tin for SMD series
Soldering characteristics	ANSI/J-STD-002B Category 3 for nanoSMDC, nanoSMDM, microSMD, miniSMDC, and miniSMDM series ANSI/J-STD-002B Category 1 for SMD series
Solder heat withstand	per IEC-STD 68-2-20, Test Tb, Section 5, Method 1A
Flammability resistance	per IEC 695-2-2 Needle Flame Test for 20 sec.
Recommended storage conditions	40°C max, 70% R.H. max; devices may not meet specified ratings if storage conditions are exceeded.

Environmental Specifications

Test	Test Method	Conditions	Resistance Change
Passive aging	Raychem PS300, Section 5.3.2	60°C, 1000 hours	±3% typical
		85°C, 1000 hours	±5% typical
Humidity aging	Raychem PS300, Section 5.3.1	85°C, 85% RH, 100 hours	±1.2% typical
Thermal shock	MIL-STD-202, Method 107G	85°C, -40°C (20 times)	-33% typical
		125°C, -55°C (10 times)	-33% typical
Vibration	MIL-STD-883C	per MIL-STD-883C	No change
Solvent resistance	Raychem PS300, Section 5.2.2	Freon	No change
		Trichloroethane	No change
		Hydrocarbons	No change

4

Agency Recognition for Surface-mount Devices*

UL	File # E74889 for all surface-mount devices
CSA	File # CA78165 for SMD/miniSMDC/miniSMDM/microSMD/nanoSMDC/nanoSMDM series
TÜV	Certificate # R9872048 for microSMD/miniSMDC/miniSMDM series Certificate # R2172061 for nanoSMDM/nanoSMDC series Certificate # R9872049 for SMD series

*Refer to Telecom and Networking section for agency recognition on Telecom and Networking Surface Mount Devices.

Table S6-A. Packaging and Marking Information for Surface-mount Devices

Part Number	Tape & Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (In.)]			Agency Recognition				
				Dimension A (Nom.)	Dimension B (Nom.)	Dimension C (Nom.)					
nanoSMDC Series											
Size 3216 mm/1206 mils											
nanoSMDC150	3,000	15,000	J	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
nanoSMDM Series											
Size 3216 mm/1206 mils											
nanoSMDM012	3,000	15,000	012	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM016	3,000	15,000	016	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM050	3,000	15,000	050	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM075	3,000	15,000	075	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM100	3,000	15,000	100	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
microSMD Series											
Size 3225 mm/1210 mils											
microSMD005	4,000	20,000	05	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD010	4,000	20,000	10	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD035	4,000	20,000	3	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD050	4,000	20,000	50	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD075	4,000	20,000	75	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD110	4,000	20,000	11	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD150	4,000	20,000	15	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
miniSMDC Series											
Size 4532 mm/1812 mils											
miniSMDC014	2,000	10,000	14	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC020	2,000	10,000	2	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC050	2,000	10,000	5	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC075	2,000	10,000	7	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC110	2,000	10,000	1	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC125	2,000	10,000	12	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC150	2,000	10,000	15	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC200	2,000	10,000	20	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC260	1,500	7,500	26	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
miniSMDM Series											
Size 4532 mm/1812 mils											
miniSMDM075	3,000	15,000	075	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM075/24	3,000	15,000	075G	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM110	3,000	15,000	110	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM110/16	3,000	15,000	110G	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM150/24	3,000	15,000	150	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM160	3,000	15,000	160	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM200	3,000	15,000	200	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM260	3,000	15,000	260	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
miniSMDE Series											
Size 11550 mm/4420 mils											
miniSMDE190	5,000	20,000	19	4.75 (0.187)	1.45 (0.057)	9.57 (0.377)	UL, CSA, TÜV				

Table S6-A. Packaging and Marking Information for Surface-mount Devices *continued*

Part Number	Tape & Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (In.)]			Agency Recognition				
				Dimension A (Nom.)	Dimension B (Nom.)	Dimension C (Nom.)					
midSMD											
Size 5050 mm/2018 mils											
SMD030-2018	4,000	20,000	A03	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD050-2018	4,000	20,000	A05	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA				
SMD100-2018	4,000	20,000	A10	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD150-2018	4,000	20,000	A15	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD200-2018	4,000	20,000	A20	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD											
Size 7555 mm/2920 mils											
SMD030	2,000	10,000	030	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD050	2,000	10,000	050	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD075	2,000	10,000	075	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD100	2,000	10,000	100	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD100/33	2,000	10,000	103	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD125	2,000	10,000	125	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD260	2,000	10,000	260	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD260-RB	2,000	10,000	260	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
SMD300	2,000	10,000	300	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
SMD2											
Size 8763 mm/3425 mils											
SMD150	1,500	7,500	150	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD150/33	1,500	7,500	153	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMDH160	1,500	7,500	160	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD185	1,500	7,500	185	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD200	1,500	7,500	200	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD250	1,500	7,500	250	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
Lead-free devices are listed in Table S6-B											
Telecom Surface-mount											
TSL250-080	1,500	7,500	T08	3.6 (0.14)	1.8 (0.07)	5.5 (0.22)	UL, CSA, TÜV				
TS250-130	1,500	7,500	T13	4.6 (0.18)	1.8 (0.07)	6.1 (0.24)	UL, CSA, TÜV				
TSV250-130	1,200	6,000	T13V	*	*	*	UL, CSA, TÜV				
TS600-170	300	900	T20	9.91 (0.390)	3.30 (0.130)	3.35 (0.132)	UL, CSA				
TS600-200-RA	300	900	T20	9.91 (0.390)	3.30 (0.130)	3.35 (0.132)	UL, CSA				
TSM600-250	200	1,000	TSM600	*	*	*	UL, CSA				

*For TSV250-130 and BM 600-250 pad layout, see Telecom and Networking Section.

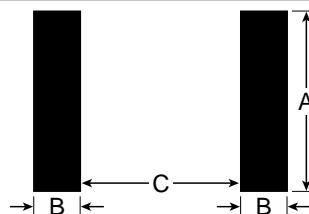
Table S6-B. Packaging and Marking Information for Lead-free Surface-mount Devices

Part Number	Tape & Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (In.)]			Agency Recognition				
				Dimension A (Nom.)	Dimension B (Nom.)	Dimension C (Nom.)					
Lead-free nanoSMDC Series											
Size 3216 mm/1206 mils											
nanoSMDC020F	3,000	15,000	02	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
nanoSMDC035F	3,000	15,000	03	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA				
nanoSMDC050F/13.2	3,000	15,000	M	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
nanoSMDC075F	3,000	15,000	L	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
nanoSMDC110F	3,000	15,000	K	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
nanoSMDC150F	3,000	15,000	J	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
Lead-free nanoSMDM Series											
Size 3216 mm/1206 mils											
nanoSMDM012F	3,000	15,000	012F	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM020F	3,000	15,000	02F	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM050F	3,000	15,000	05F	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM050F/13.2	3,000	15,000	5FG	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM075F	3,000	15,000	07F	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
nanoSMDM100F	3,000	15,000	10F	1.80 (0.071)	1.00 (0.039)	1.5 (0.059)	UL, CSA, TÜV				
Lead-free microSMD Series											
Size 3225 mm/1210 mils											
microSMD005F	4,000	20,000	05F	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD010F	4,000	20,000	10	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD035F	4,000	20,000	3	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD050F	4,000	20,000	50	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD075F	4,000	20,000	75	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD110F	4,000	20,000	11	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
microSMD150F	4,000	20,000	15	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV				
Lead-free miniSMDC Series											
Size 4532 mm/1812 mils											
miniSMDC014F	2,000	10,000	14	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC020F	2,000	10,000	2	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC050F	2,000	10,000	5	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC075F	2,000	10,000	7	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC110F	2,000	10,000	1	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
			110F								
miniSMDC110F/16	2,000	10,000	16V	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC125F	2,000	10,000	12	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC125F/16	2,000	10,000	125F								
			16V								
miniSMDC150F	2,000	10,000	15	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC160F	2,000	10,000	16	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC200F	2,000	10,000	20	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC260F	1,500	7,500	26	3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				
miniSMDC260F/12	1,500	7,500	260F								
			12V								
				3.15 (0.124)	1.78 (0.070)	3.45 (0.136)	UL, CSA, TÜV				

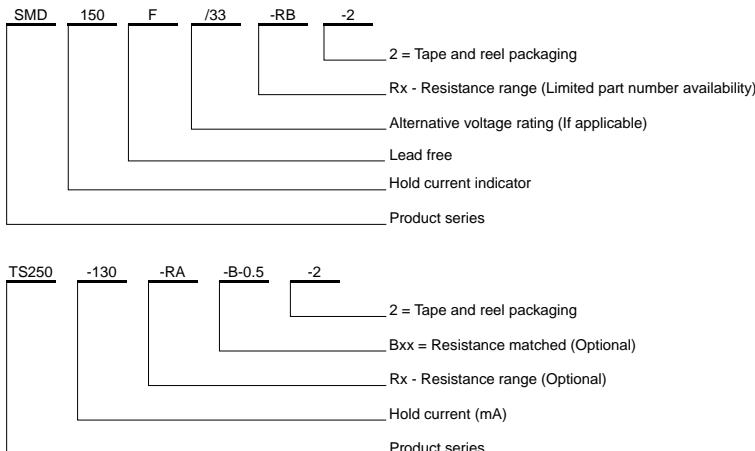
Table S6-B. Packaging and Marking Information for Lead-free Surface-mount Devices *continued*

Part Number	Tape & Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (In.)]			Agency Recognition				
				Dimension A (Nom.)	Dimension B (Nom.)	Dimension C (Nom.)					
Lead-free miniSMD Series											
Size 4532 mm/1812 mils											
miniSMDM075F/24	3,000	15,000	07FG	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM110F	3,000	15,000	110F	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM110F/16	3,000	15,000	11FG	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM200F	3,000	15,000	200F	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
miniSMDM260F	3,000	15,000	260F	3.20 (0.126)	1.50 (0.059)	2.50 (0.098)	UL, CSA, TÜV				
Lead-free midSMD Series											
Size 5050 mm/2018 mils											
SMD030F-2018	4,000	20,000	A03F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD100F-2018	4,000	20,000	A10F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD150F-2018	4,000	20,000	A15F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD200F-2018	4,000	20,000	A20F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
Lead-free SMD Series											
Size 7555 mm/2920 mils											
SMD030F	2,000	10,000	030F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD050F	2,000	10,000	050F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD075F	2,000	10,000	075F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD075F/60	2,000	10,000	075F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA				
SMD100F	2,000	10,000	100F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD100F/33	2,000	10,000	103F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD125F	2,000	10,000	125F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD260F	2,000	10,000	260F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
SMD300F	2,000	10,000	300F	4.6 (0.18)	1.50 (0.059)	3.4 (0.134)	UL, CSA, TÜV				
Lead-free SMD2 Devices											
Size 8763 mm/3425 mils											
SMD150F	1,500	7,500	150F	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD150F/33	1,500	7,500	153F	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD185F	1,500	7,500	185F	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD200F	1,500	7,500	200F	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				
SMD250F	1,500	7,500	250F	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	UL, CSA, TÜV				

4

Figure S20. Recommended Pad Layout

Part Numbering System



Solder Reflow and Rework Recommendations for Surface-mount Devices

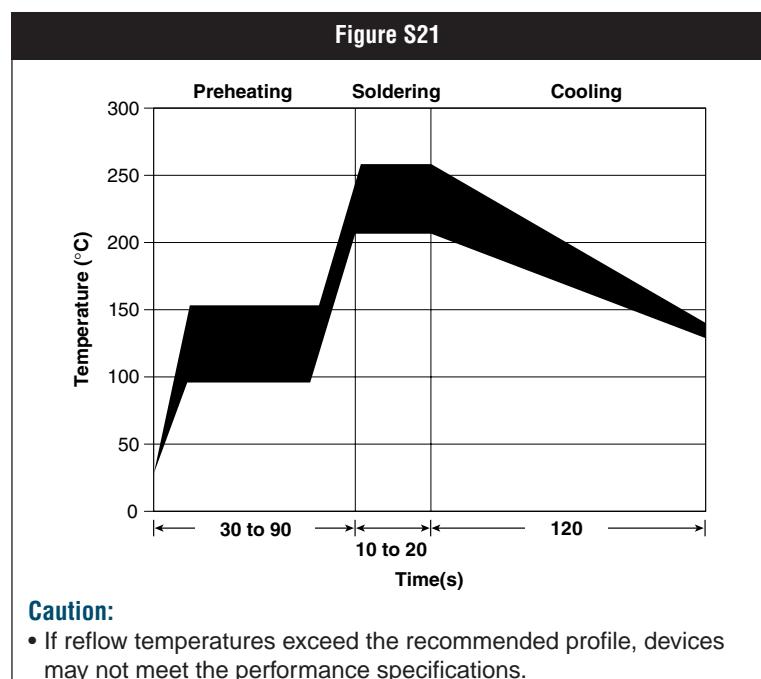
Solder Reflow

- Recommended reflow methods: IR, Vapor phase, and hot air oven.
- The following product series are not designed to be wave soldered to circuit boards:
 - nanoSMDM
 - miniSMDM
 - midSMD
 - SMD
 - SMD2
 - TS

- The following product series are designed to be wave soldered to circuit boards:

nanoSMDC
microSMD
miniSMDC, miniSMDE

- Recommended maximum paste thickness for the microSMD, miniSMDC, and miniSMDE devices is 0.25 mm (10mils), 0.13-0.25 mm for miniSMDM and nanoSMDM, and 0.38 mm for SMD.
- Devices can be cleaned using standard methods and solvents.



Rework

- Use standard industry practices for the nanoSMDC, nanoSMDM, microSMD, miniSMDC, miniSMDM, and miniSMDE devices.

- For SMD and midSMD series and all TS devices rework should be confined to removal of the installed product and replacement with a fresh device.

Table S7. Tape and Reel Specifications for Surface-mount Devices (in Millimeters)

	nanoSMDC nanoSMDM	microSMD	miniSMDC miniSMDM	miniSMDE190	midSMD	SMD	SMD2
	EIA 481-1	EIA 481-1	EIA 481-1	EIA 481-2	EIA 481-2	EIA 481-2	EIA 481-2
W	8.0 ± 0.30	8.0 ± 0.30	12.0 ± 0.30	24.0 ± 0.30	16.0 ± 0.30	16.0 ± 0.30	16.0 ± 0.30
P _o	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10
P ₁	4.0 ± 0.10	4.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10	12.0 ± 0.10
P ₂	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.10	2.0 ± 0.10	2.0 ± 0.10	2.0 ± 0.10
A _o	Table S7a	2.9 ± 0.10	Table S7b	5.70 ± 0.10	5.11 ± 0.15	5.6 ± 0.23	6.9 ± 0.23
B _o	Table S7a	3.5 ± 0.10	Table S7b	11.90 ± 0.10	5.6 ± 0.23	8.1 ± 0.15	9.6 ± 0.15
B ₁ max.	4.35	4.35	8.2**	20.1	12.1	12.1	12.1
D _o	1.5 + 0.10/- .00	1.5 + 0.10/- .00	1.5 + 0.10/- .00	1.5 + 0.10/- .00	1.5 + 0.10/- .00	1.5 + 0.10/- .00	1.5 + 0.10/- .00
F	3.5 ± 0.05	3.5 ± 0.05	5.5 ± 0.05	11.5 ± 0.10	7.5 ± 0.10	7.5 ± 0.10	7.5 ± 0.10
E ₁	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10
E ₂ min.	6.25	6.25	10.25	22.25	14.25	14.25	14.25
T max.	0.6	0.6	0.6	0.6	0.6	0.6	0.6
T ₁ max.	0.1	0.1	0.1	0.1	0.1	0.1	0.1
K _o	Table S7a	0.90 ± 0.10*	Table S7b	0.95 ± 0.10	1.8 ± 0.15	3.2 ± 0.15	3.4 ± 0.15
Leader min.	390***	390	390***	400	400	400	400
Trailer min.	160***	160	160***	160	160	160	160

*1.1±0.05 for microSMD150

**5.9 for miniSMDM

***200 for nanoSMDM, miniSMDM

Table S7a

	nanoSMDC150	nanoSMDM
A _o	2.3 ± 0.10	1.88 ± 0.10
B _o	3.5 ± 0.10	3.5 ± 0.10
K _o	1.45 ± 0.10	1.4 ± 0.10

Table S7b

	miniSMDC	miniSMDC260	miniSMDM
A _o	3.5 ± 0.23	3.7 ± 0.10	3.5 ± 0.23
B _o	5.1 ± 0.15	4.9 ± 0.10	5.1 ± 0.15
K _o	0.9 ± 0.15	1.4 ± 0.10	2.3 ± 0.15

Table S7c. Reel Dimensions for Surface-mount Devices (in millimeters)

	nanoSMDC nanoSMDM	microSMD	miniSMDC	miniSMDM	miniSMDE190	midSMD	SMD	SMD2
A max.	180	180	180	340	330	330	330	330
N min.	50	50	50	50	60	50	50	50
W ₁	8.5 + 1.5/- .00	8.4 + 1.5/- .00	12.4 + 2.0/- .00	12.4 + 2.0/- .00	24.4 + 2.0/- .00	16.4 + 2.0/- .00	16.4 + 2.0/- .00	16.4 + 2.0/- .00
W ₂ max.	14.4	14.4	18.4	18.4	30.4	22.4	22.4	22.4

Figure S21. EIA Taped Component Dimensions

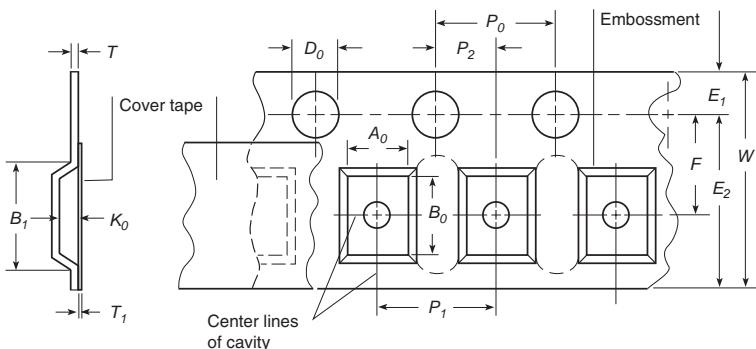
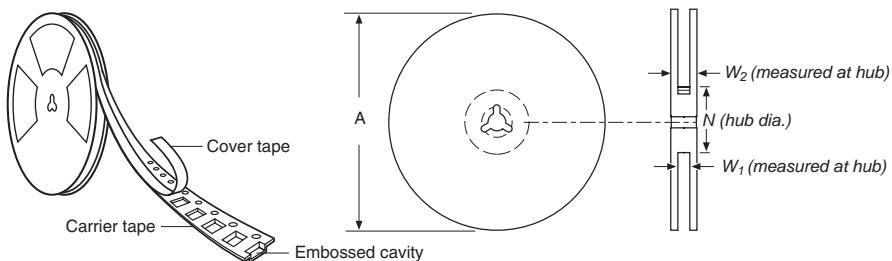


Figure S22. EIA Reel Dimensions



Latest Information

- Please visit us at www.circuitprotection.com or contact your local representative for the latest information.
- The information in this data package contains some preliminary information. Raychem Circuit Protection, a division of Tyco Electronics, reserves the right to change any of the specifications without notice. In addition, Tyco Electronics reserves the right to make changes—without notification to Buyer—to materials or processing that do not affect compliance with any applicable specification.



WARNING:

- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- The devices are intended for protection against occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Operation in circuits with a large inductance can generate a circuit voltage ($L \frac{di}{dt}$) above the rated voltage of the PolySwitch resettable device.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помошь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помошь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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